

# P54/74FCT651T/AT/CT — P54/74FCT652T/AT/CT OCTAL TRANSCEIVER/REGISTER

## FEATURES

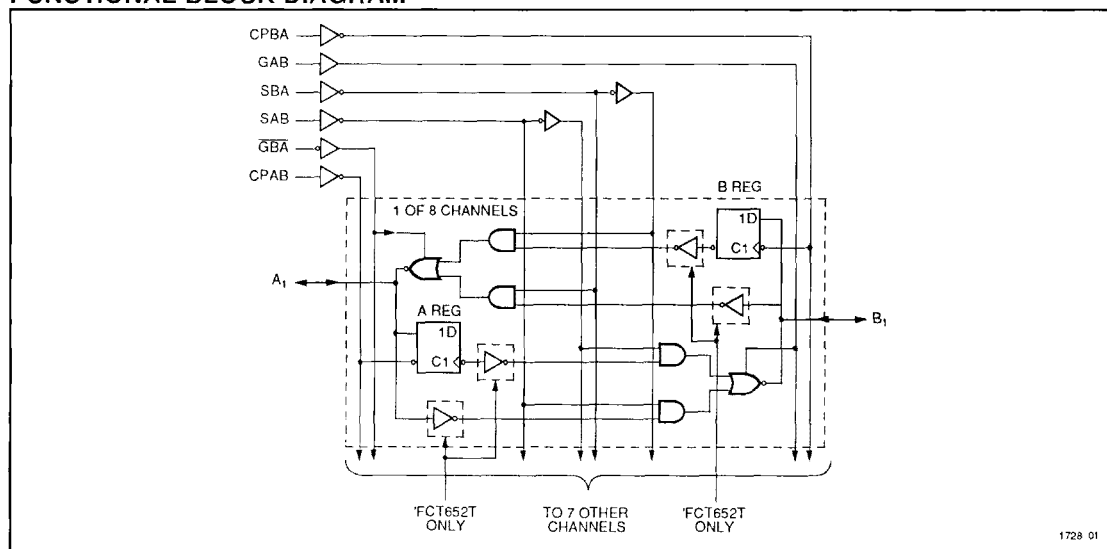
- Function, Pinout and Drive Compatible with the FCT and F Logic
- FCT-C speed at 5.4ns max. (Com'l)  
FCT-A speed at 6.3ns max. (Com'l)
- Reduced  $V_{OH}$  (typically = 3.3V) versions of Equivalent FCT functions
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- ESD protection exceeds 2000V
- Power-off disable feature
- Matched Rise and Fall times
- Fully Compatible with TTL Input and Output Logic Levels
- 64 mA Sink Current (Com'l), 48 mA (Mil)  
15 mA Source Current (Com'l), 12 mA (Mil)
- Independent Register for A and B Buses
- Multiplexed Real-Time and Stored Data Transfer
- Bidirectional Bus Transceiver and Registers
- Manufactured in 0.7 micron PACE Technology™

## DESCRIPTION

THE 'FCT651T and 'FCT652T consist of bus transceiver circuits, D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal storage registers. GAB and GBA control pins are provided to control the transceiver functions. SAB and SBA control pins are provided to select either real-time or stored data transfer. The circuitry used for select control will eliminate the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input level selects real-time data and a high selects stored data.

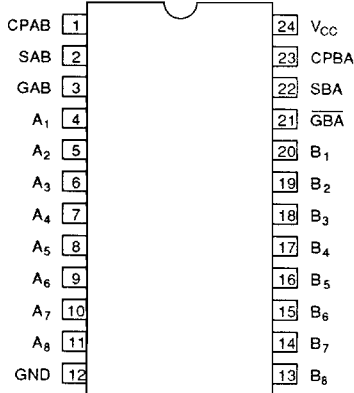
Data on the A or B data bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (CPAB or CPBA), regardless of the select or enable control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling GAB and GBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state.

## FUNCTIONAL BLOCK DIAGRAM

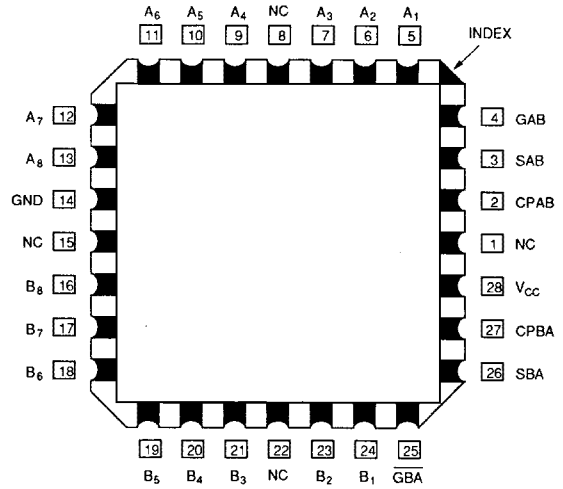




## PIN CONFIGURATIONS



DIP (D4, P4)  
SOIC (S4)



LCC (L5-1)

**ABSOLUTE MAXIMUM RATINGS<sup>1,2</sup>**

Symbol	Parameter	Value	Unit
$T_{STG}$	Storage Temperature	-65 to +150	°C
$T_A$	Ambient Temperature Under Bias	-65 to +135	°C
$V_{CC}$	$V_{CC}$ Potential to Ground	-0.5 to +7.0	V
$P_T$	Power Dissipation	0.5	W

1728 Tbl 01

**Notes:**

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

Symbol	Parameter	Value	Unit
$I_{OUTPUT}$	Current Applied to Output	120	mA
$V_{IN}$	Input Voltage	-0.5 to +7.0	V
$V_{OUT}$	Voltage Applied to Output	-0.5 to +7.0	V

1728 Tbl 02

2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either  $V_{CC}$  or ground.

**RECOMMENDED OPERATING CONDITIONS**

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

1728 Tbl 03

Supply Voltage ( $V_{CC}$ )	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

1728 Tbl 04

**DC ELECTRICAL CHARACTERISTICS** (Over recommended operating conditions)

Symbol	Parameter	Min	Typ <sup>1</sup>	Max	Units	$V_{CC}$	Conditions
$V_{IH}$	Input HIGH Voltage	2.0			V		
$V_{IL}$	Input LOW Voltage			0.8	V		
$V_H$	Hysteresis <sup>3</sup>		0.2		V		All inputs
$V_{IK}$	Input Clamp Diode Voltage		-0.7	-1.2	V	MIN	$I_{IN} = -18\text{mA}$
$V_{OH}$	Output HIGH Voltage	Military Commercial	2.4 2.4	3.3 3.3	V	MIN MIN	$I_{OH} = -12\text{mA}$ $I_{OH} = -15\text{mA}$
$V_{OL}$	Output LOW Voltage	Military Commercial	0.3 0.3	0.55 0.55	V	MIN MIN	$I_{OL} = 48\text{mA}$ $I_{OL} = 64\text{mA}$
$I_I$	Input HIGH Current			20	$\mu\text{A}$	MAX	$V_{IN} = V_{CC}$
$I_{IH}$	Input HIGH Current (Except I/O Pins)			5	$\mu\text{A}$	MAX	$V_{IN} = 2.7\text{V}$
$I_{IL}$	Input LOW Current (Except I/O Pins)			-5	$\mu\text{A}$	MAX	$V_{IN} = 0.5\text{V}$
$I_{IH}$	Input HIGH Current (I/O Pins only)			15	$\mu\text{A}$	MAX	$V_{OUT} = 2.7\text{V}$
$I_{IL}$	Input LOW Current (I/O Pins only)			-15	$\mu\text{A}$	MAX	$V_{OUT} = 0.5\text{V}$
$I_{OS}$	Output Short Circuit Current <sup>2</sup>	-60	-120	-225	mA	MAX	$V_{OUT} = 0.0\text{V}$
$I_{OFF}$	Power-off Disable			100	$\mu\text{A}$	0V	$V_{OUT} = 4.5\text{V}$
$C_{IN}$	Input Capacitance <sup>3</sup>		5	10	pF	MAX	All inputs
$C_{IO}$	I/O Capacitance <sup>3</sup>		9	12	pF	MAX	All outputs
$I_{CC}$	Quiescent Power Supply Current		0.2	1.5	mA	MAX	$V_{IN} \leq 0.2\text{V}$ , $V_{IN} > V_{CC} - 0.2\text{V}$

1728 Tbl 05

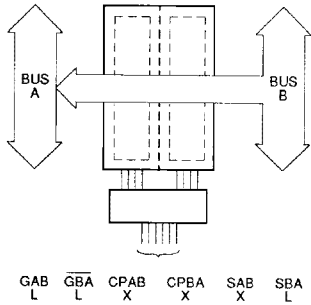
**Notes:**

- Typical limits are at  $V_{CC} = 5.0\text{V}$ ,  $T_A = +25^\circ\text{C}$  ambient.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

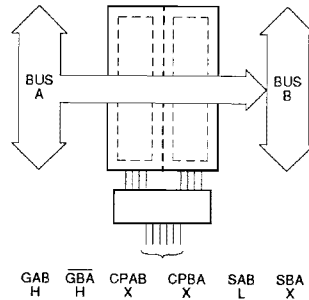
- This parameter is guaranteed but not tested.

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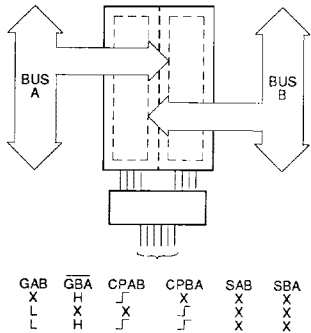
REAL-TIME TRANSFER  
BUS B TO BUS A

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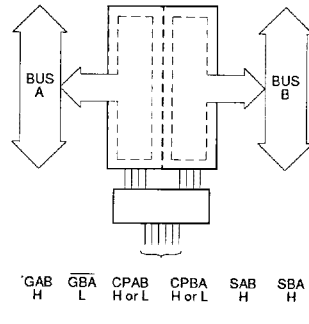
REAL-TIME TRANSFER  
BUS A TO BUS B

1727 04



STORAGE FROM  
A AND/OR B

1727 05



TRANSFER STORED  
DATA TO A AND/OR B

1727 06

**Note:**

1. Cannot transfer data to A bus and B bus simultaneously.

**FUNCTION TABLES**

Inputs						Data I/O		Operation or Function	
GAB	GBA	CPAB	CPBA	SAB	SBA	A <sub>1</sub> thru A <sub>8</sub>	B <sub>1</sub> thru B <sub>8</sub>	'FCT651T	'FCT652T
L	H	H or L	H or L	X	X	Input	Input	Isolation Store A and B Data	Isolation Store A and B Data
X	H		H or L	X	X <sup>2</sup>	Input Input	Unspecified <sup>1</sup> Output	Store A, Hold B Store A in both registers	Store A, Hold B Store A in both registers
L	X	H or L		X	X <sup>2</sup>	Unspecified <sup>1</sup> Output	Input Input	Hold A, Store B Store B in both registers	Hold A, Store B Store B in both registers
L	L	X	X	X	L	Output	Input	Real-Time B Data to A Bus Stored B Data to A Bus	Real-Time B Data to A Bus Stored B Data to A Bus
L	L	X	H or L	X	H	Output	Input	Real-Time B Data to A Bus Stored B Data to A Bus	Real-Time B Data to A Bus Stored B Data to A Bus
H	H	X	X	L	X	Input	Output	Real-Time A Data to B Bus Stored A Data to B Bus	Real-Time A Data to B Bus Stored A Data to B Bus
H	H	H or L	X	H	X	Input	Output	Real-Time A Data to B Bus Stored A Data to B Bus	Real-Time A Data to B Bus Stored A Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored A Data to B Bus and Stored B Data to A Bus	Stored A Data to B Bus and Stored B Data to A Bus

**Notes:**

1. The data output functions may be enabled or disabled by various signals at the GAB or GBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.
2. Select control = L: clocks can occur simultaneously.  
Select control = H: clocks must be staggered in order to load both registers.  
H = HIGH, L = LOW, X = Don't Care,  $\downarrow$  LOW-to-HIGH Transition

1728 Tbl 06

**DC CHARACTERISTICS** (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ <sup>1</sup>	Max	Units	Conditions
$\Delta I_{CC}$	Quiescent Power Supply Current (TTL inputs)	0.5	2.0	mA	$V_{CC} = \text{MAX}$ , $V_{IN} = 3.4V^2$ , $f_1 = 0$ , Outputs Open
$I_{CCD}$	Dynamic Power Supply Current <sup>3</sup>	0.15	0.25	mA/ MHz	$V_{CC} = \text{MAX}$ , One Input Toggling, 50% Duty Cycle, Outputs Open $GAB = \text{GND}$ , $\overline{GAB} = \text{GND}$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
$I_C$	Total Power Supply Current <sup>5</sup>	1.7	4.0	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz}$ , $GAB = \text{GND}$ , $\overline{GAB} = \text{GND}$ , $SAB = \text{CPAB} = \text{GND}$ , $SBA = V_{CC}$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		2.2	6.0	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz}$ , $GAB = \text{GND}$ , $\overline{GAB} = \text{GND}$ , $SAB = \text{CPAB} = \text{GND}$ , $SBA = V_{CC}$ , $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$
		7.0	12.8 <sup>4</sup>	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 5\text{MHz}$ , $GAB = \overline{GAB} = \text{GND}$ , $SAB = \text{CPAB} = \text{GND}$ , $SBA = V_{CC}$ , $V_{IN} = 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		9.2	21.8 <sup>4</sup>	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 5\text{MHz}$ , $GAB = \overline{GAB} = \text{GND}$ , $SAB = \text{CPAB} = \text{GND}$ , $SBA = V_{CC}$ , $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$

**Notes:**

- Typical values are at  $V_{CC} = 5.0V$ , +25°C ambient.
- Per TTL driven input ( $V_{IN} = 3.4V$ ); all other inputs at  $V_{CC}$  or GND.
- This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- Values for these conditions are examples of the  $I_{CC}$  formula. These limits are guaranteed but not tested.
- $$I_C = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$$

$$I_C = I_{CC} + \Delta I_{CC} \cdot D_H \cdot N_T + I_{CCD} (f_0/2 + f_1 N_1)$$

$$I_{CC} = \text{Quiescent Current with CMOS input levels}$$

$$\Delta I_{CC} = \text{Power Supply Current for a TTL High Input } (V_{IN} = 3.4V)$$

$D_H$  = Duty Cycle for TTL Inputs High

$N_T$  = Number of TTL Inputs at  $D_H$

$I_{CCD}$  = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

$f_0$  = Clock Frequency for Register Devices (Zero for Non-Register Devices)

$f_1$  = Input Frequency

$N_1$  = Number of Inputs at  $f_1$

All currents are in milliamps and all frequencies are in megahertz.

7

1728 Tbl 07

### AC CHARACTERISTICS

Symbol	Parameter	'FCT651T/652T				'FCT651AT/652AT				'FCT651CT/652CT				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
$t_{PLH}$ $t_{PHL}$	Propagation Delay Bus to Bus	2.0	11.0	2.0	9.0	2.0	7.7	2.0	6.3	1.5	6.0	1.5	5.4	ns	1, 5
$t_{PZH}$ $t_{PZL}$	Output Enable Time Enable to Bus	2.0	15.0	2.0	14.0	2.0	10.5	2.0	9.8	1.5	8.9	1.5	7.8	ns	1, 5
$t_{PHZ}$ $t_{PLZ}$	Output Disable Time Enable to Bus	2.0	11.0	2.0	9.0	2.0	7.7	2.0	6.3	1.5	7.7	1.5	6.3	ns	1, 5
$t_{PLH}$ $t_{PHL}$	Propagation Delay Clock to Bus	2.0	10.0	2.0	9.0	2.0	7.0	2.0	6.3	1.5	6.3	1.5	5.7	ns	1, 7, 8
$t_{PLH}$ $t_{PHL}$	Propagation Delay SBA or SAB to A or B	2.0	12.0	2.0	11.0	2.0	8.4	2.0	7.7	1.5	7.0	1.5	6.2	ns	1, 7, 8

1728 Tbl 08

**Note:**

1. AC Characteristics guaranteed with  $C_L = 50pF$  as shown in Figure 1.

### AC OPERATING REQUIREMENTS

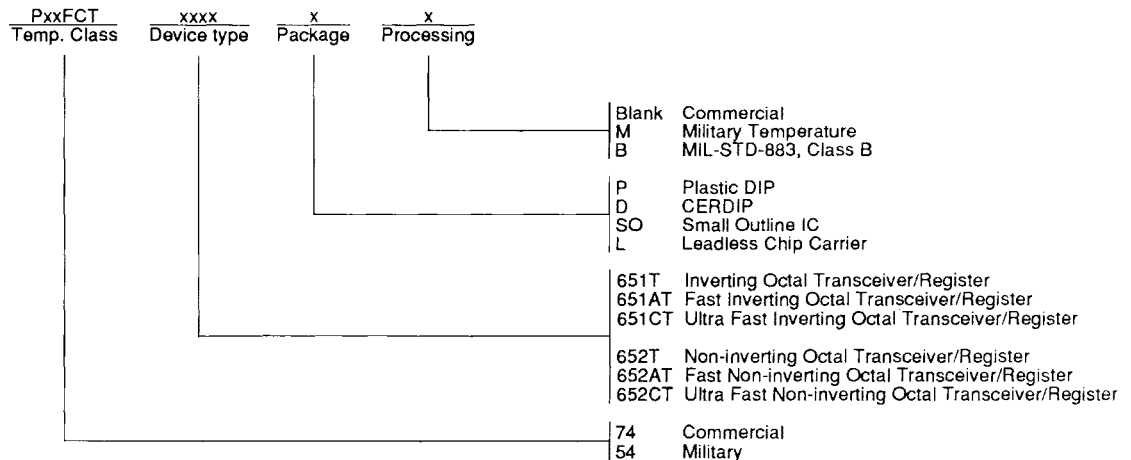
Symbol	Parameter	'FCT651T/652T				'FCT651AT/652AT				'FCT651CT/652CT				Units	Fig. No.
		MIL		COM'L		MIL		COM'L		MIL		COM'L			
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
$t_s(H)$ $t_s(L)$	Setup Time HIGH or LOW Bus to Clock	4.5	—	4.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	1, 4
$t_h(H)$ $t_h(L)$	Hold Time HIGH or LOW Bus to Clock	2.0	—	2.0	—	1.5	—	1.5	—	1.5	—	1.5	—	ns	1, 4
$t_w(H)$ $t_w(L)$	Clock Pulse Width, HIGH or LOW	6.0	—	6.0	—	5.0	—	5.0	—	5.0	—	5.0	—	ns	1, 5

1728 Tbl 09

**Notes:**

- Minimum limits are guaranteed but not tested on Propagation Delays.
- With one data channel toggling,  $t_w(L) = t_w(H) = 4.0ns$  and  $t_r = t_f = 1.0ns$ .

### ORDERING INFORMATION



1728 07